

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) Device for electrostatically maintaining a wafer of conductor or semi-conductor material, comprising an electrically insulating soleplate (1) on which the wafer (2) is arranged, at least two pairs of electrodes (7), (8), (9), and (10), where the electrodes of each pair are subjected, through inverters, to a voltage difference generated by a power supply (6) that supplies a D.C. voltage and thus creates an intense electric field, wherein said electrodes are arranged under the insulating surface, wherein the ~~electrode pairs are supplied cyclically at different polarities~~ inverters cyclically invert a polarity of the voltage difference between the electrodes of each electrode pair in a manner so that at any moment at least one electrode pair holds the wafer.

2. (previously presented) Device according to claim 1, wherein the electrodes are concentric rings.

3. (currently amended) Device according to claim 1, wherein the arrangement of electrodes is symmetrical or concentric relative to the center of the soleplate (1).

4. (currently amended) Device according to Claim 1, wherein [[a]] planar surfaces of the two electrodes forming one pair have the same area.

5. (previously presented) Device according to Claim 1, wherein a surface of contact between the wafer and the adhesion device have geometric variations.

6. (previously presented) Device according to Claim 1, wherein said electrodes and the dielectric layer (23) are made by serigraphy of thick films on a base plate (22).

7. (cancelled)

8. (previously presented) Device according to Claim 1, wherein each electrode (7), (8), (9) and (10) is split in two.

9. (previously presented) Device according to Claim 1, wherein frequency of commutation of the electrodes is between 0.01 Hz and 1 Hz.